

O I P E DOCKET NO. 12980F383US0

FEB 19 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sailesh Chittipendi, et al.
Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

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Sir:

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Attached is a copy of the Official Filing Receipt received from the Patent and Trademark Office in this application.

Please amend the Attorney Docket No. on the Official Filing Receipt to: CHITTIPEDDI 59-108.

Respectfully submitted,

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTORNEY DOCKET NO.	DRWGS	TOT CL	IND CL
09/467,253	12/20/99	2811	\$760.00	374 129.80E389US0	5	20	3

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2796-4
SAILESH CHITTI PEDDI

CHITTI PEDDI 59-108

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts of Application" ("Missing Parts Notice") in this application, please submit any corrections to this Filing Receipt with your reply to the "Missing Parts Notice." When the PTO processes the reply to the "Missing Parts Notice," the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s) SAILESH CHITTI PEDDI, ALLENTOWN, PA; SAILESH MANSINH MERCHANT, ORLANDO, FL.

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TITLE

WIRE BONDING METHOD FOR COOPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

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